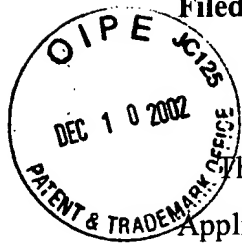


Appl. No.  
Filed

: 09/9987,232  
: November 6, 2001



VERSION WITH MARKINGS TO SHOW CHANGES MADE

This application is related to and claims the benefit of the filing of U.S. Provisional Application No. 60/331,021, entitled Thermoelectric Hetrostructure Assemblies Element, filed October 24, 2001.

H:\DOCS\SCJ\SCJ-5614.DOC  
120402

RECEIVED  
DEC 12 2002  
TC 1700